

WHAT IS CLAIMED IS:

1. A thin-film capacitor element comprising:  
an insulative substrate having a via hole filled with a  
5 conductive material;  
a lower electrode;  
a dielectric layer; and  
an upper electrode; wherein the lower electrode, the  
dielectric layer, and the upper electrode are successively  
10 deposited in order on the insulative substrate, wherein  
either one of the lower electrode and the upper electrode  
connects to the end face of the conductive material; and  
the dielectric layer is shaped like a ring to surround the  
via hole.

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2. A thin-film capacitor element according to Claim 1,  
wherein the dielectric layer is shaped like a ring with the via  
hole as the center.

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3. A thin-film capacitor element according to Claim 1,  
wherein the insulative substrate is made of low-temperature-  
sintered ceramic.